

Specification of Aluminium Base PCB

Performance Index	Products	Domestic substrate
Peeling strength(n/mm)		1.8
Insulation resistance (ω)		>1*10g
Breakdown voltage (vdc)		4k
Soakable soldering ($^{\circ}$ C/m)		280 $^{\circ}$ C,1min,no bubble, delamination
Thermal conductivity (w/m-k)		>0.8
Thermal resistance ($^{\circ}$ C/w)		<1.2
Combustibility		v-o
Dielectric constant (1mhz)		4
Dielectric loss angle(tangent)		0.03

items	Ability
Product model	Al substrate cu substrate
Material model	Domestic al imported al
Surface disposal	Spray tin/ chemical tin/chemical Gold/osp/ immersion tin
Layers	Single-side al substrate / double-side Al substrate /four-layer al substrate
Maximum measurement	1100mm*480mm
Minimum measurement	5mm*5mm
Line width/space	0.1mm
Warp and twist	$\leq 0.5\%$ (thickness:1.6mm, Measurement:300mm \times 300mm)
Processing thickness	0.3–4.5mm
Copper foil thickness	35um 70um 105um 140um
Molding dimension tolerance	± 0.15 mm
V-cut positioning accuracy	± 0.1 mm
Processing capability	6000m ²
Cu thickness of inner aperture	20-25um
Aperture location deviation	± 0.076 mm
Minimum diameter of piercing	Lower than1.0mm 1.0mm 1.2-3.0mm 1.5mm
Minimum specification of the square groove	Plate-thickness Lower than 1.0mm 0.8mm \times 0.8mm Plate-thickness

	1.2-3.0mm 1.0×1.0mm
Circuit printing deviation	±0.076mm
Scope of molding dimension tolerance	CNC: ±0.1mm punching the shape: ±0.15mm
Mini aperture	0.8mm not limited to the maximum aperture diameter
Coating thickness	Gold plating: Ni 2.5-5um Au 0.05-0.1um & 0.025- 0.075um
	Immersion gold: Ni 5-8um Au0.08-0.1um
	Spray tin 3-30um 4-30um
V-cut angle deviation	±5°
Scope of v-cut plates	0.6mm-3.2mm
Marking fond of smallest component	0.15mm
Smallest windowing of pad	0.01mm